Towards single ion-single photon strong coupling for quantum networking

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Sensitive compensation of micromotion in 3 dimensions for a surface-electrode ion trap using lock-in detection

Micromotion - the driven motion of an ion displaced from the null of the RF trapping field - broadens and shifts atomic transitions, leaks in noise from the RF supply, and interferes with ion coupling to integrated trap elements. Because stray electric fields readily build-up from charge deposition during ion loading or photoelectric charge creation from laser fields¹, micromotion is exacerbated as traps are miniaturized and dielectric materials introduced. the correlated scattering rate:

Precise compensation of stray electric fields is essential for a trapped ion qubit: <1% broadening of Doppler-cooling transition -> need ion within ~0.7 um of RF null <1% reduction in strength of carrier transition (for qubit rotations) -> need ion within ~400 nm of RF null

Resolved sideband spectroscopy on a narrow atomic transition can extract the micromotion amplitude by comparing the Rabi frequency of the first micromotional sideband and the carrier transition². A simpler scheme detects the modulation of the fluorescence at the RF frequency due to the varying Doppler shift of the cooling beam over an RF cycle. However, neither of these techniques can detect offsets out of the trap plane:

Micromotion measurement technique:	Out-of-plane compensation?	Compensation without access to narrow transition?	Integration time required for 10 nm positioning accuracy:	
Resolved sideband	no ^(a)	no	~40 ms	
RF correlation	no ^(a)	yes	~300 ms	
Synchronous tickle	yes	yes	~6 ms ^(b)	
(a) Typically (unless the RF trapping potential is tilted) (b) Assuming a tickle voltage of I V is applied				
I. S. X. Wang et al., J. Appl. Phys. 110, 104901 (2011). 3. N. Daniilidis et al., New J. Phys. 13, 013032 (2011). 2. D. Berkeland et al., J. Appl. Phys. 83, 10 (1998). 4. M. Drewsen et al., Phys. Rev. Lett. 93, 243201 (2004).				



digital lock-in detection of the ion's driven secular motion.



Can ion traps be manufactured with the same process as an IBM processor? A "trap-on-a-chip" CMOS (complementary metal-oxide-semiconductor) fabrication process is the ultimate platform in terms of reproducibility and precision for open source ion traps as well as scalability and integration with other CMOS photonic devices.

layer and the aluminum interconnect layer.

Trap design considerations:

- \bullet Buried metal layers beneath trap







lues	Light collection efficiency	Power at the detector	Detector quantum efficiency		
	30%	60 pW	30%		
MT	5%	10 pW	20%		
I. A.M. Eltony et al., Appl. Phys. Lett. New J. Phys. 102, 054106 (2013).					

CMOS trap (Collaboration with Karan Mehta and Rajeev Ram)